



Material Content Data Sheet



Sales Product Name		BTS3410G		Issued		20. July 2018		
MA#		MA000362322						
Package		PG-DSO-8-25		Weight*		83.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.231	2.66	2.66	26624	26624
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		428	
	non noble metal	iron	7439-89-6	0.717	0.86		8559	
wire	non noble metal	copper	7440-50-8	29.121	34.75	35.66	347545	356639
	noble metal	gold	7440-57-5	0.825	0.98	0.98	9845	9845
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1155
encapsulation	plastics	epoxy resin	-	4.453	5.31		53149	
	inorganic material	silicondioxide	60676-86-0	43.856	52.35	57.78	523403	577707
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9713	9713
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7760	7760
glue	plastics	epoxy resin	-	0.172	0.20		2050	
	noble metal	silver	7440-22-4	0.810	0.97	1.17	9662	11712
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com